



NAN YA PLASTICS CORPORATION
ELECTRONIC MATERIALS DIVISION.
COPPER CLAD LAMINATE DEPARTMENT
NO. 201. TUNG HWA N. ROAD, TAIPEI, TAIWAN.

Glass cloth base modified resin
flame retardant copper clad laminate

NP-530

■ FEATURES

- Low dielectric constant and low dissipation factor at high frequency range
- Greater design flexibility by allowing the same impedance
- Suit for Antenna、Base station、PA and LNB application
- Excellent dimensional stability

■ PERFORMANCE LIST

Characteristics		Unit	Conditioning	Typical Values	SPEC	Test Method
Permittivity	Process	-	10GHz/23°C	3.08	-	2.5.5.5
	Design	-	-	2.98		Differential phase length
Loss Tangent		-	10GHz/23°C	0.0030	-	2.5.5.5
		-		0.0029		SPDR
Volume resistivity		MΩ·cm	C-96/35/90	4x 10 ⁸ ~5x 10 ⁹	10 ⁶ ↑	2.5.17
Surface resistivity		MΩ	C-96/35/90	5x 10 ⁷ ~5x 10 ⁸	10 ⁴ ↑	2.5.17
Arc resistance		SEC	D-48/50+D-0.5/23	120↑	60 ↑	2.5.1
Dielectric breakdown		KV	D-48/50	60 ↑	40 ↑	2.5.6
Moisture absorption		%	D-24/23	0.01~0.02	0.35 ↓	2.6.2.1
Flammability		-	C-48/23/50	94V0	94V0	UL94
Peel strength 1 oz		lb/in	288°C x 10" solder floating	6~8	-	2.4.8
Thermal stress		SEC	288°C dipping	300 ↑	10 ↑	2.4.13.1
Pressure cooker 2 hr (2 atm 121°C)		SEC	288°C dipping	300 ↑	N/A	-
Dimensional stability X-Y axis		%	E-0.5/170	0.010~0.030	0.050 ↓	2.4.39
Coefficient of thermal expansion Z-axis before Tg		ppm/°C	TMA	20~30	N/A	2.4.24
Glass transition temp		°C	DMA	230	N/A	2.4.25
Td (5% weight loss)		°C	TGA, 10°C/min	420	325 ↑	-

NOTE:

Data shown are nominal values for reference only.

The average value in the table refers to

samples of .0307" 1/1.

Test method per IPC-TM-650

■ PRODUCT SIZE & THICKNESS

THICKNESS INCH (mm)	THICKNESS TOLERANCE	COPPER CLADDING OZ (μm)	SIZE INCH	SIZE mm
0.0057"(0.145)	±0.0007"(0.018)			
0.0107"(0.272)	±0.0010"(0.025)			
0.0207"(0.529)	±0.0020"(0.050)	0.5 (17) HTE,RTF	49 x 37	1245 x 0940
0.0307"(0.780)	±0.0020"(0.050)	1.0 (35) HTE,RTF	49 x 41.1	1245 x 1045
0.0407"(1.034)	±0.0030"(0.076)		49 x 43	1245 x 1092
0.0607"(1.542)	±0.0030"(0.076)			

* Use resin coating copper, need to plasma after desmear process.